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Soldering Pad Using Image Processing

Yash Sonawane,
Department of EXTC
VPPCOE&VA, Sion
Harshal Kanojia
Department of EXTC
VPPCOE&VA, Sion

Prajwal Gurav
Department of EXTC
VPPCOE&VA, Sion

Nilesh Nadekar
Department of EXTC
VPPCOE&VA, Sion

Project Guide-Prof. Rajesh Khotre
Department of EXTC
VPPCOE&VA, Sion

ABSTRACT— This paper examines various methods for detecting and analyzing defects in printed circuit boards using image processing. Currently PCBs are the main component of electronic assembly. Since PCBs are an important part of the electronics industry, any mistake in PCB soldering will ultimately lead to the failure of the entire circuit or the entire product market. The traditional book review process is time-consuming, labor-intensive, and prone to human error. Therefore, automated systems need to be implemented quickly to increase the efficiency and accuracy of the error detection process. Therefore, we prepared our study to detect and identify various PCB faults using a combination of neural network algorithms using image processing technology and Matlab software. The proposed project will involve the design and implementation of a machine that can identify various aspects of medical devices, such as defective materials, connectors, and malfunctions, using image processing algorithms. The system uses computer vision technology to analyze high-resolution bandage images from digital cameras or imaging equipment. This method uses image analysis algorithms to analyze and evaluate the bandage to improve the overall quality control process. This research leads to the advancement of the analysis of electrical systems in the power generation industry through the integration of computer vision, providing a more reliable and faster assessment.

I. INTRODUCTION

Printed circuit boards (PCBs) use electronic components, pads, and other features etched from copper sheets laminated to a non-conductive substrate for mechanical support and electrical connection. PCBs can be single-sided (single layer of copper), double-sided (two layers of copper), or multilayer (outside and inside). Multilayer PCBs allow more devices. Conductors of different systems are connected by covering them with paths called vias. High-end PCBs may contain components such as capacitors, resistors, or active components on the substrate.

One of the main products of the electronics industry is PCB production. Visual inspection is often the biggest cost of PCB design. It is responsible for detecting cosmetic and functional defects and often causes them. PCB inspection has two main functions; defect detection and defect classification. There are currently many algorithms using contact or non-contact for PCB fault detection [1]. The contact method measures the connectivity of the circuit but cannot detect the defect in appearance. There are many options for non-contact testing, including x-ray tests, ultrasound tests, thermal tests, and optical tests that use image processing. These systems suffer from fatigue, slowness, and higher costs than manual scanning. Proper management of electrical power is crucial to ensure the reliability and performance of electrical equipment. Solder pads are an essential part of circuit boards and play an important role in supporting the connection of electronic components. In recent years, the PCB industry has needed automation for many reasons. One of the most important of these is the development of technology in PCB design and production. New electronic manufacturing technologies require high-quality PCB design and small sample sizes. Designs and conventions create challenges in the book review [5] process. Another important factor is the need to shorten the review time. These factors have led to the automation of the PCB industry. Nowadays, automatic systems are popular in the manufacturing industry to increase efficiency.

In recent years, image processing techniques have emerged as a promising solution for automating the detection of soldering pad defects. By leveraging advancements in computer vision, pattern recognition, and machine learning, these techniques offer a fast, accurate, and non-destructive approach to identifying various types of defects, such as insufficient solder, solder bridges, and misalignment.

Table-1. Defects on Single Layer Bare PCB

no	Defect Name
1	Breakout
2	Pin Hole
3	Open circuit
4	Under etch
5	Mouse-bite
6	Missing conductor
7	Spur
8	Short
9	Wrong size hole
10	Conductor too close
11	Spurious copper
12	Excessive short
13	Missing hole
14	Over etch

The following table provides information about the various defects caused during PCB soldering. This paper presents a comprehensive overview of the state-of-the-art methods for soldering pad defect detection using image processing. We review the key challenges associated with manual inspection and discuss how image processing techniques address these challenges. Additionally, we delve into the various image processing algorithms and methodologies employed for defect detection, including thresholding, edge detection, feature extraction, and classification.

Furthermore, we explore recent advancements in deep learning-based approaches, such as convolutional neural networks (CNNs), which have shown remarkable performance in defect detection tasks. We discuss their strengths, limitations, and potential for enhancing the accuracy and efficiency of soldering pad defect detection systems.

Through this review, we aim to resolve the problems arising in the Soldering and PCB manufacturing industry. We also aim to provide researchers and practitioners in the field of electronics manufacturing with valuable insights into the current landscape of soldering pad defect detection using image processing. By highlighting the advantages and limitations of existing methods, we seek to inspire further research and development efforts towards more robust and reliable defect detection solutions, ultimately contributing to the improvement of electronic device reliability and quality assurance processes.

Working of the project:

Machine vision inspection techniques are necessary in today's manufacturing. Printed circuit boards (PCBs) have many flaws, imperfections, and faulty connections. Visual or visual inspection is often the biggest cost of a PCB. New PCB inspection software should be developed to reduce production costs resulting from manufacturing costs. There are three processes: 1) Fault detection 2) Fault location 3) Fault classification This process is done before the installation of electrical and electronic equipment. There are currently many algorithms for error detection using image processing. < br>

In this article, we can use contactless information based on images as a detection and classification technique. A copy of the faulty PCB image and the faulty PCB inspection image are segmented and compared with the extracted image and other programs. PCB defects can be divided into two categories: functional defects and cosmetic defects. Improper operation may seriously affect the performance of the PCB or cause its failure. Poor decoration may affect the appearance of the PCB but may affect its performance in the long run due to abnormal heat dissipation and current distribution. As shown in Table I, there are 14 mysteries for single-layer bare PCBs. Figure 2 shows the binary image of single layer bare PCB [2] and Figure 3 shows the same image with parameters as listed [2]. In Table 1 [4].

Key components of the proposed system include:

1. Image Acquisition Module: This module will be responsible for capturing a good image of the packaging from the electronic board. It may involve the integration of a digital camera or specialized equipment that can capture detailed images of the pad in different lighting conditions.

2. Pre-processing Module: Pre-process the original images captured by the camera to improve image quality, reduce noise and improve the accuracy of the defect algorithm. Advanced technologies such as noise reduction, contrast enhancement and image normalization will be used in this model.

3. Defect Detection Module: This module, the core of the system, uses image processing algorithms to detect defects. Techniques such as thresholding, edge detection and feature extraction will be used to identify different types of defects in the fabric. Machine learning algorithms including convolutional neural networks (CNN) can also be used for cognitive performance. 4. User Interface: The system will feature a user-friendly interface for interacting with the software and visualizing defect detection results. Users will be able to input images, initiate defect detection processes, and view detected defects along with relevant information.

4. User interface: The system will have a user interface to interact with the software and view error detection results. Users will be able to access images, initiate defect detection procedures, and track defects and related information.

The proposed project will be implemented using hardware and software tools accessible to students. It will provide students with hands-on experience in graphics, computer vision, and software development while solving real-world problems in electrical engineering.

Through this program, students will gain important skills in design, algorithm development and project management and prepare them for the engineering and technology of the future. Moreover, the design process can also be used in the production of electronic products in industry, helping to improve the quality control process and reliability of electronic products.

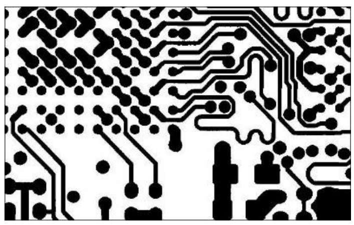


Fig. 2. Binary image of perfect PCB which is given in figure 1

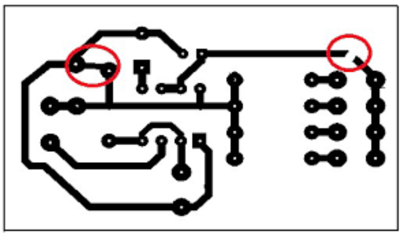


Fig. 3. Binary image of above PCB with certain defects

CODE AND ALGORITHMS:

PCBs contain individual electronic devices and their connections. Defects in PCBs can result in poor performance or product failures.

By detecting defects in PCBs, production lines can remove faulty PCBs and ensure that electronic devices are of high quality.

For the software component, MATLAB serves as our primary tool. We utilize it for processing both template and original images, each with unique specifications.

The transformation from color to grayscale involves several preprocessing steps, including image adjustment, enhancement, and contrast adjustment. Additionally, we ensure uniformity in image dimensions, adjusting them to a standard size of 244x244 pixels through image division.

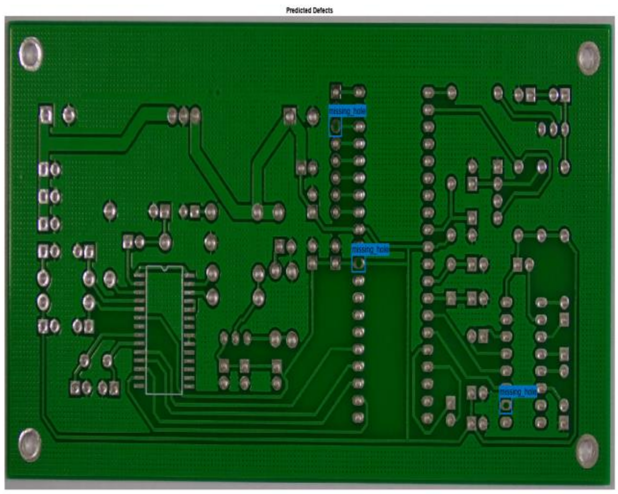
The Canny edge detection algorithm plays a crucial role in our process. It operates through multiple stages to effectively identify edges in images while minimizing noise and preserving essential features. This algorithm computes matrices for both the inspection and template images, enabling the calculation of the number of components present.

We implement a monomodal configuration to enhance accuracy, achieving a reduction in diversion of up to 0.01% for both images.

For error calculation and fault recognition, we leverage a pre-trained neural network specifically tailored for printed circuit board (PCB) analysis, utilizing the PCB defect dataset. This dataset comprises 1,386 images of PCB components, each synthesized to simulate various defects.

These defects encompass missing holes, mouse bites, open circuits, short circuits, spurs, and spurious copper. Notably, each image contains multiple instances of defects within the same category but located in different areas. The dataset includes detailed bounding box and coordinate information for every defect across all images, facilitating precise object detection and error identification.

In the preparation of data training, several steps are undertaken, including analyzing object class distribution, partitioning data, augmenting training data, training the detector, evaluating the detector, and assessing object size-based detection metrics.



II. CURRENT STATE OF THE ART

Harshal from VPP proposed a method using neural networks to classify PCB defects. This algorithm divides the image into original patterns. There are raw patterns, pattern patterns, normalization patterns, and classifications created using binary morphological image processing and learning vector quantization (LVQ) neural networks. PCB defects can be divided into three categories; front defects only, rear defects only, and front and rear defects

Yash from VPP created a pixel-based workflow and comparison. At the time of writing this article, the algorithm is designed only for classifying defects; a pixel-based method to classify multiple defects; There are various stages in this method, including segmentation, windowing, defect detection, model assignment. normalization. and distribution

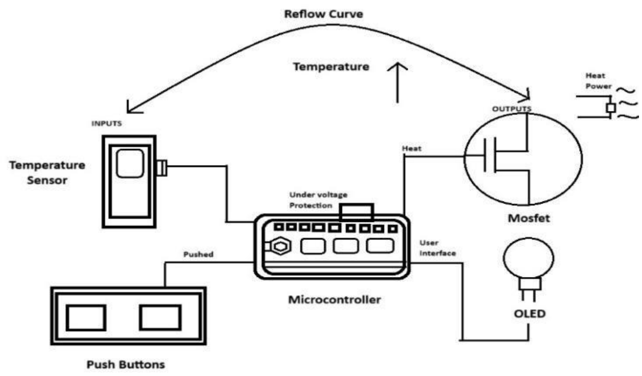
Nilesh at VPP proposed method process that consists of two stages. The first stage is analysis, and the second stage is the neural network that will detect the defect. First, 558 training samples were used to train the system proposed here. The first level indicates that the standard contrast index is the best display index. In the second stage, neural networks are used to classify defects, and the results show that more than three parameters should be used to identify defects.

The algorithm proposed by Prajwal on VPP can be used on bare PCB to detect and identify defects. PCB assembly is wrong. However, the main limitation of this algorithm is that the proposed algorithm only works on binary images when the camera output is in grayscale mode. Although conversion from grayscale to binary format is possible, errors may occur. Therefore, the algorithm needs to be developed to decode the grayscale image format. Additionally, during the computational process of detecting defects and transactions, this process will introduce unnecessary noise due to correlation and non-uniform binarization. Therefore, unwanted noise needs to be taken into account to improve the algorithm. So far, the proposed algorithm could only classify 14 defects into five groups.

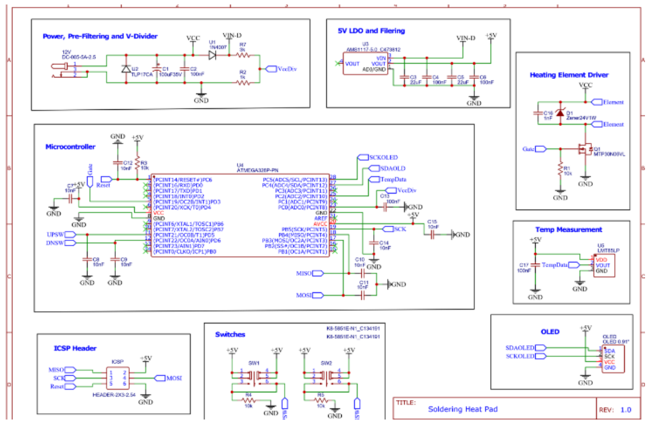
Nilesh at VPP sought improvement in Prajwal's work by dividing it into seven groups. This is done by combining image processing algorithms and segmentation algorithms. Each image is split into four samples, and then five new images are created for each pair of segmented reference and test images, resulting in 20 new images. Among these, seven images were successfully classified as false. The result of this particular experiment is that there is 1 defect in each group, with a maximum of 4 defects, thus increasing the work done by Khalid from 5 to 7.

LAYOUT OF THE PROJECT:

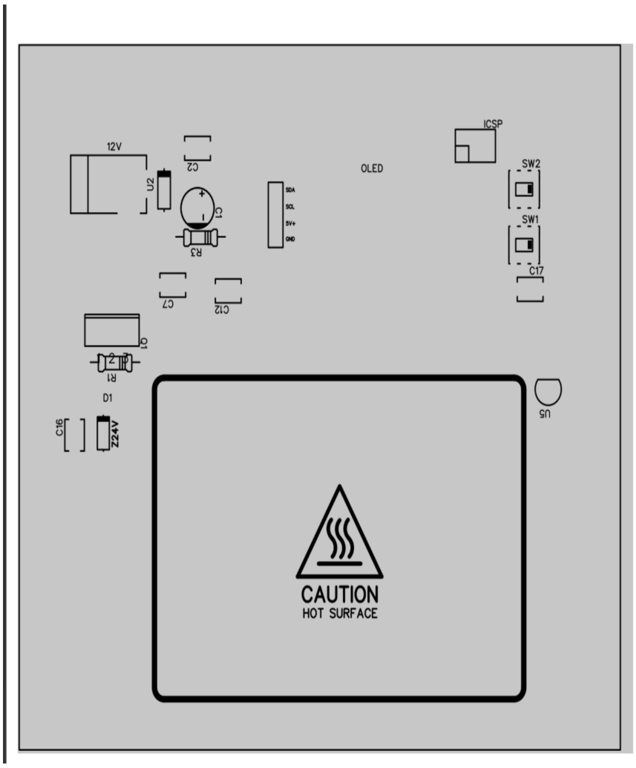
(1) Block Diagram for Soldering Pad Hardware Components:



(2) Schematic diagram for the project:



(3) Component placement:



(4) PCB simulation of Top and Bottom layers:

Fig(a): Top layer

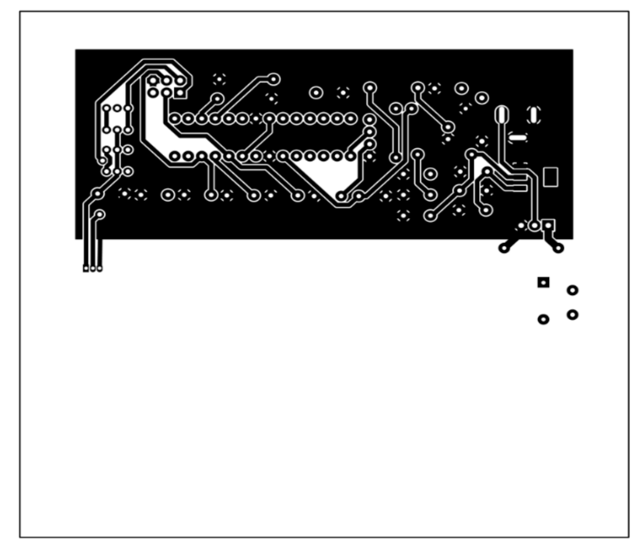
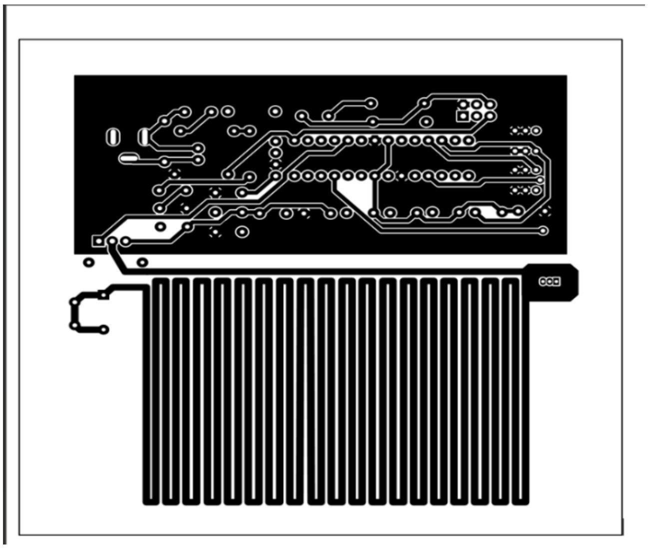


Fig (b): Bottom layer



III. APPLICATIONS

The quality of PCBs will have a huge impact on the performance of many electronic devices. Bare PCB refers to a PCB without electronic components placed on it and is used with other components to create electronic components. Bare PCB should be checked to reduce the production cost of bad PCB usage. Computer technology has been developed and used in many industries. One of these applications is visual inspection of PCBs. Blind analysis is important because it eliminates the issue and provides a rapid and quantitative assessment. Responsible for detecting cosmetic and functional defects and continues to ensure 100% product quality on all finished products.

The various applications are discussed in brief below.

1.Quality Assurance in electrical engineering:
Solder pad flaw detection is an important aspect of safety in electrical engineering. Image processing systems detect problems such as insufficient solder, solder bridges and misalignment, enabling companies to maintain quality standards and prevent bad products from arriving from customers.

2. Automated inspection system:
Image processing based defect inspection system provides a reliable and effective manual inspection method. By scanning large volumes of image pads, these systems can improve accuracy and consistency while reducing inspection times and processing costs.

3. Real-time process monitoring:
Combining machine images with production tools can be used to monitor the welding process in real time. By regularly monitoring the display pad, companies can detect deviations from appropriate standards and implement corrective measures to improve poor processes.

4. Preventive maintenance:
Seal fault detection systems can also support strategic maintenance by monitoring soldering equipment in real time. Early detection of defects or deficiencies leads to taking preventive measures, reducing downtime and preventing defective equipment.

5. Research and Development:
Image processing provides a better understanding of the root causes of pad defects, allowing researchers to develop new solutions to improve the manufacturing process and equipment. By identifying patterns and defects, researchers can optimize the welding process, increase product composition, and improve product reliability.

6. Quality control of electrical equipment:
In the electrical equipment industry, it is important to inspect the fabric to ensure the reliability and safety of electronic equipment. By integrating imaging technology into the production line, manufacturers can detect defects early in the production process, thus reducing the risk of product returns and Approval.

7. Adherence to industry standards:
Adherence to industry standards and regulations is essential in electronics manufacturing. Image-based defect detection aids compliance with standards such as IPC-A-610 and ISO 9001 by providing objective and quantitative measurements to assess product quality and compliance with regulatory requirements.
In summary, the application of defect buffering ranges from quality assurance and process optimization to research and development. Use image processing technology to expand into many areas. By leveraging the resources of this technology, manufacturing companies can improve product quality, increase operational efficiency, and maintain a competitive advantage in the global market.

VII.INDUSTRY USAGE

Soldering pad defect detection is an important factor in ensuring the quality and reliability of electronic components in the industry. With the development of image processing technology, automatic flaw detectors have been widely used in various electronic industries. This article provides an overview of the commercial applications of medical imaging, focusing on key applications, challenges, and future trends.

The need for quality products containing defects in the electronics industry has led to the use of automatic inspection systems. Imaging technology provides a non-destructive and effective way to detect defects such as solder joints, insufficient solder and pad misalignment. These systems enable companies to achieve high levels of product quality and reliability while reducing production costs and cycle times.

One of the main applications of optical fiber is surface mount technology (SMT) assembly lines. These machines are integrated into the existing production process, enabling instant inspection of the packaging to verify the quality of the product. These systems can prevent the production of faulty electronics by detecting defects early in the manufacturing process, thus reducing labor and spare parts costs.

Negative mask is used in SMT assembly line as well as electronics, printing and other fields. Board (PCB) assembly and semiconductor manufacturing facilities. These systems allow companies to have a high level of control throughout the entire production process, from raw material control to the final stage of the product.

Although image-based negative detection has many advantages, there are still some difficulties in its commercial use. These challenges include integrating audits with existing production tools, standardizing audit procedures and performance metrics, and implementing vulnerability detection capability to deal with big data.

Looking ahead, future trends in the industry include the use of advanced learning technologies such as deep learning and learning support for search and distribution. This technique provides greater accuracy and robustness in detecting defects and changes in the shape of the pillow. Additionally, the integration of error analysis with robotic inspection tools and Internet of Things (IoT) tools will increase the effectiveness and efficiency of quality control procedures in energy production.

In short, the use of image-based error detection technology has become an indispensable tool for the electronic manufacturing industry to ensure product quality and reliability. By addressing current challenges and embracing future perspectives, companies can continue to use technology to increase innovation and competitiveness in the global marketplace.

VIII.CONCLUSION

PCB manufacturing has seen many advances in the last decade. Machine vision can meet the needs of the manufacturing industry to improve product quality and increase productivity. This work provides a review of PCB visual inspection algorithms. The main limitation of all existing findings is that all algorithms need specialized hardware platforms to achieve the desired real-time performance, making the systems very expensive. It is also important to effectively verify PCB defect detection and classification with image capture systems such as cameras, camcorders, and personal computers. This algorithm is used only for binary images and the camera's output is in grayscale mode. While converting from grayscale to binary format has some pitfalls, the algorithm needs to be improved to handle grayscale image format.In PCB inspection system a noise elimination system is designed in such a way that the resultant defects found in this algorithm is more precise. This algorithm is developed to work with binary images only, whereas the output from the camera is in gray scale format. Although the conversion can be made from gray scale to binary format imperfection can be occurred this algorithm should be improved to handle the gray scale image format.

In this article we provide an overview of existing methods for detecting defects in fabric using image processing tools. We discuss the importance of defect detection in the reliability and performance of electronic circuit boards, highlighting the limitations of the inspection process.Traditional and resourceful images follow the path.

From our analysis, it is clear that image processing technology holds great promise in detecting defects on the pad, from simple initialization and search edge algorithms to deep learning such as Convolutional Neural Network (CNN). This technology performs best in detecting various types of defects with high efficiency and productivity, improving process control and reducing production costs.

Furthermore We also discuss the integration of operational images with robotic inspection tools to detect defects in a real-time operating environment. Using computer vision, these machines can analyze high-resolution images of fabric with unprecedented accuracy and precision, providing companies with valuable insight into the quality of their products.

However, despite the significant progress made in this field, several challenges remain to be addressed. These include the need for annotated training data, the development of efficient algorithms for handling large-scale image datasets, and the integration of defect detection systems into existing manufacturing workflows. Addressing these challenges requires continued research and development efforts, as well as interdisciplinary collaboration between researchers in computer vision, electronics manufacturing, and quality assurance.

In conclusion, progress in detecting pad defects using image processing technology holds great promise for the development of medical bandages. Reliability and efficiency of electronic production processes. By improving existing methods, exploring new algorithmic methods, and overcoming remaining challenges, we can improve the quality of electronic products and contribute to the raising of the level of all electronic devices.

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